Mitsubishi Materials Corporation to Exhibit at the 2025 IEEE 74th Electronic Components and Technology Conference (ECTC), Booth #135!

Mitsubishi Materials Corporation is thrilled to announce our participation in the 2025 IEEE 75th Electronic Components and Technology Conference (ECTC), alongside our subsidiary, Mitsubishi Materials USA Corporation. This premier international event will be held in Dallas, TX, from May 28 to May 29, 2025.

Also, we are pleased to announce that on Friday, the 30th, during the program session, we will be presenting a lecture titled 'A Study About Bonding Properties With Multilayer Porous Structures for Fine Pitch Interconnection.' This presentation will focus on our latest development of nanoporous Cu plating solution for advanced packaging applications.

Under our commitment "For people, society and the earth, circulating resources for a sustainable future", Mitsubishi Materials Corporation will showcase our latest advancements in low alpha tin-silver plating chemistry and nanoporous Cu fine pitch bonding technologies for next-generation advanced interconnections.

Key highlights include:

Low Alpha Pb-Free Solder Plating Solution and Anode: We will present our latest low alpha Pb-free solder products for various bump formations (Sn and SnAg for C4 bump, and micro bump). Solder bump plating plays a crucial role in advanced packaging, and Mitsubishi Materials leads the industry with over 20 years of experience, commanding over 60% of the global market share!

Nanoporous Cu Plating: We will showcase our latest innovation in nanoporous Cu plating technology for next-generation advanced interconnections.

Semiconductor-Related Products: Explore our cutting-edge semiconductor materials, including AuSn alloy paste and large square Si substrate materials.

Visit our **booth #135** to engage with our experts and learn more about our contributions to the future of electronic components and technology. For additional information and conference registration, please visit the IEEE ECTC website.

2025 IEEE 75th Electronic Components and Technology Conference
https://www.ectc.net/index.cfm
Mitsubishi Materials Booth #135

CONFERENCE & EXHIBITION LOCATION:
Gaylord Texan Resort & Convention Center
1501 Gaylord Trail, Grapevine, Texas, USA, 76051.

EXHIBITION HOURS:
Wednesday, May 28/ 9:00am–12:30pm, 2:00 –6:30pm
Thursday, May29/ 9:00am–12:30pm,2:00 -4:00pm

ECTC
2025
75 YEARS

2025 ECTC EXHIBITION

Exhibit Hall Hours

Wednesday, May 28
9:00 a.m. – 12:30 p.m. & 2:00 p.m. – 6:30 p.m.

Thursday, May 29
9:00 a.m. – 12:30 p.m. & 2:00 p.m. – 4:00 p.m.